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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Applicant Young-Joon Park, et al. Docket Number: TI-35623

Serial No.: 10/628,198 Art Unit: 2814

Filed: 07/28/03 Examiner: Ginette Peralta

For: A Two Step Semiconductor Manufacturing Process for
Copper Interconnects

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NAME OF INVENTOR(S):	
Young-Joon Park, et al.	
RECEIPT DATE & SERIAL NO.:	
Serial No.: 10/628,198	
Filing Date: 07/28/03	
TITLE OF INVENTION: A Two Step Semiconductor Manufacturing Process for Copper Interconnects	
TI FILE NO.:	DEPOSIT ACCT. NO.:
TI-35623	20-0668
FAXED: 8-18-05 DUE: 5-22-05 ATTY/SEC'Y: RAK/kjv	

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Texas Instruments Incorporated
PO Box 655474, M/S 3909
Dallas, TX 75265-5474